

Precision Operational Amplifiers

The LM11C is a precision, low drift operational amplifier providing the best features of existing FET and Bipolar op amps. Implementation of super gain transistors allows reduction of input bias currents by an order of magnitude over earlier devices such as the LM308A. Offset voltage and drift have also been reduced. Although bandwidth and slew rate are not as great as FET devices, input offset voltage, drift and bias current are inherently lower, particularly over temperature. Power consumption is also much lower, eliminating warm—up stabilization time in critical applications.

Offset balancing is provided, with the range determined by an external low resistance potentiometer. Compensation is provided internally, but external compensation can be added for improved stability when driving capacitive loads.

The precision characteristics of the LM11C make this device ideal for applications such as charge integrators, analog memories, electrometers, active filters, light meters and logarithmic amplifiers.

Low Input Offset Voltage: 100 μV

Low Input Bias Current: 17 pA

Low Input Offset Current: 0.5 pA

Low Input Offset Voltage Drift: 1.0 μV/°C

Long–Term Stability: 10 μV/year

• High Common Mode Rejection: 130 dB

LM11C, CL

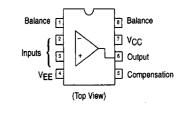
PRECISION OPERATIONAL AMPLIFIERS

SEMICONDUCTOR TECHNICAL DATA



N SUFFIX PLASTIC PACKAGE CASE 626

PIN CONNECTIONS



ORDERING INFORMATION

Device	Operating Temperature Range	Package		
LM11CN,CLN	T _A = 0° to +70°C	Plastic DIP		

MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Power Supply Voltage	V _{CC} to V _{EE}	40	Vdc	
Differential Input Current (Note 1)	IID	±10	mA	
Output Short Circuit Duration (Note 2)	tsc	Indefinite		
Power Dissipation (Note 3)	PD	500	mW	
Operating Junction Temperature	Tj	85	°C	
Storage Temperature Range	T _{stg}	-55 to +125	°C	

ELECTRICAL CHARACTERISTICS (T_J = 25°C, unless otherwise noted [Note 4] .)

Characteristic	Symbol	Min	Тур	Max	Min	Тур	Max	Unit
Input Offset Voltage T _{IOW} to T _{high}	VIO	-	0.2	0.6 0.8	-	0.5 -	5.0 6.0	m∨
Input Offset Current T _{low} to T _{high}	110	-	1.0	10 20	- -	4.0 -	25 50	pА
Input Bias Current T _{low} to T _{high}	IB	-	17 -	100 150	-	17	200 300	рA
Input Resistance	ri	_	1011	_	-	1011	_	Ω
Input Offset Voltage Drift Tlow to Thigh	ΔV _{ΙΟ} /ΔΤ	-	2.0	5.0	-	3.0	-	μV/°C
Input Offset Current Drift Tlow to Thigh	ΔΙ _{ΙΟ} /ΔΤ	_	10		-	50	-	fA/°C
Input Bias Current Drift T _{low} to T _{high}	ΔΙ _{ΙΒ} /ΔΤ	_	0.8	3.0	_	1.4	-	pA/°C
Large Signal Voltage Gain $V_S=\pm 15\ V,\ V_{Out}=\pm 12\ V,\ I_{Out}=\pm 2.0\ mA$ $T_{low}\ to\ T_{high}\ (Note\ 5)$ $V_S=\pm 15\ V,\ V_{Out}=\pm 12\ V,\ I_{Out}=\pm 0.5\ mA$ $T_{low}\ to\ T_{high}$	Avol	100 50 250 100	300 - 1200 -		25 15 50 30	300 - 800 -		V/mV
Common Mode Rejection $V_S = \pm 15 \text{ V, } -13 \text{ V} \le V_{CM} \le 14 \text{ V}$ $V_S = \pm 15 \text{ V, } -12.5 \text{ V} \le V_{CM} \le 14 \text{ V, } T_{low} \text{ to } T_{high}$	CMR	110 100	130	-	96 90	110	_	dB
Power Supply Rejection $\pm 2.5 \text{ V} \le \text{V}_S \le \pm 20 \text{ V}$ T_{low} to T_{high}	PSR	100 96	118	-	84 80	100	-	dB
Power Supply Current Tlow to Thigh	ΙD	-	0.3	0.8 1.0	-	0.3	0.8	mA
Output Short Circuit Current T _J = 150°C, Output Shorted to Ground	ISC	-	±10	-	-	±10	-	mA

NOTES: 1. The inputs are shunted by back-to-back diodes for over-voltage protection. Excessive current will flow if the input differential voltage is in excess of 1.0 V if no limiting resistance is used. Additionally, a 2.0 kΩ resistance in each input is suggested to prevent possible latch-up initiated by supply reversals.

^{2.} The output is current limited when shorted to ground or any voltages less than the supplies. Continuous overloads will require package dissipation to be considered and heatsinking should be provided when necessary.

^{3.} Devices must be derated based on package thermal resistance (see package outline dimensions).

4. These specifications apply for VEE +2.0 V ≤ VCM ≤ VCC −1.0 V (VEE +2.5 V ≤ VCM ≤ VCC −1.0 V for Tlow to Thigh) and ±2.5 V ≤ VS ≤ ±20 V Tlow to Thigh; 0°C ≤ TJ ≤ +70°C for LM11C and LM11C.

5. Vout = ±11.5 V, all other conditions unchanged.

Figure 1. Input Bias Current versus Case Temperature 50 40 IB, INPUT BIAS CURRENT (pA) 30 $V_{CC}/V_{EE} = \pm 2.0 V$ 20 10 -10 -20 $V_{CC}/V_{EE} = \pm 2.5 V$ -30 -40 -50 -25 -50 25 50 75 100 125 150 TC, CASE TEMPERATURE (°C)

versus Case Temperature 40 IO, INPUT OFFSET CURRENT (pA) 30 Curve 1, VCC/VEE = ±20 V 2, $V_{CC}/V_{EE} = \pm 2.5 \text{ V}$ 20 10 0 0 25 50 75 100 150 125 TC, CASE TEMPERATURE (°C)

Figure 2. Input Offset Current

Figure 3. Temperature Coefficient of Input Offset Voltage versus Input Offset Voltage

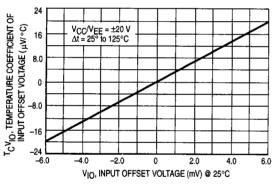


Figure 4. Spectral Noise Density

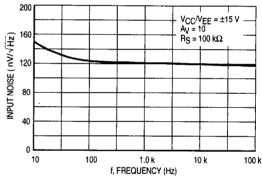


Figure 5. Common Mode Limits versus Temperature

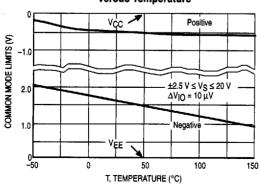
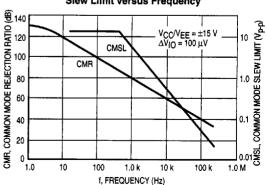


Figure 6. Common Mode Rejection and Slew Limit versus Frequency



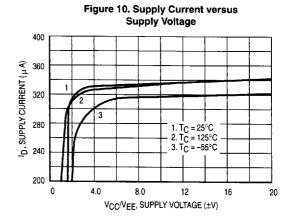
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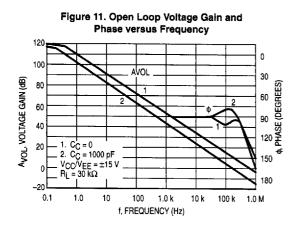
VCC/VEE, SUPPLY VOLTAGE (±V)

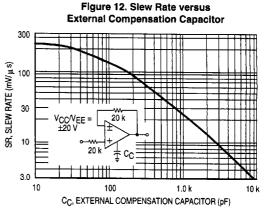
versus Load Current Vsat, OUTPUT SATURATION VOLTAGE (V) -1.0 $\begin{array}{l} -55^{\circ}C \leq T_{C} \leq 125^{\circ}C \\ \pm 2.5 \ V \leq V_{S} \leq \pm 15 \ V \end{array}$ -2.0 $\Delta V_{10} = 10 \,\mu V$ $\Delta V_{10} = 20 \,\mu V (125^{\circ}C)$ 2.0 1.0 ٧EE 0 0 1.0 2.0 3.0 4.0 IL, LOAD CURRENT (±mA)

Figure 8. Output Saturation

Figure 9. Power Supply Rejection Ratio versus Frequency 120 PSR, POWER SUPPLY REJECTIOJN (dB) 100 80 60 ٧EE 40 Vcc 20 0 10 100 1.0 k 10 k 100 k 10 M 1.0 M f, FREQUENCY (Hz)







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1.0 k 20, OUTPUT IMPEDANCE (Ω) 100 Av = 100010 V_{CC}/V_{EE} = ±15 V lout = ±1.0 mA 1.0 $A_{V} = 1.0$ 0.1 0.01 100 k 10 100 1 0 k 10 k 1.0 M 10 M

Figure 13. Closed Loop Output Impedance versus Frequency

APPLICATIONS INFORMATION

f. FREQUENCY (Hz)

Due to the extremely low input bias currents of this device, it may be tempting to remove the bias current compensation resistor normally associated with a summing amplifier configuration. Direct connection of the inputs to a low impedance source or ground should be avoided when supply voltages greater than approximately 3.0 V are used. The potential problem involves reversal of one supply which can cause excessive current to flow in the second supply. Possible destruction of the IC could result if the second supply is not current limited to approximately 100 mA or if bypass capacitors greater than 1.0 μF are used in the supply bus.

Disconnecting one supply will generally cause reversal due to loading of the other supply within the IC and in external circuitry. Although the problem can usually be avoided by placing clamp diodes across the power supplies of each printed circuit board, a careful design will include sufficient resistance in the input leads to limit the current to 10 mA if the input leads are pulled to either supply by internal currents. This precaution is not limited only to the LM11C.

The LM11C is capable of resolving picoampere level signals. Leakage currents external to the IC can severely impair the performance of the device. It is important that high quality insulating materials such as teflon be employed. Proper cleaning to remove fluxes and other residues from

printed circuit boards, sockets and the device package are necessary to minimize surface leakage.

When operating in high humidity environments or temperatures near 0°C, a surface coating is suggested to set up a moisture barrier.

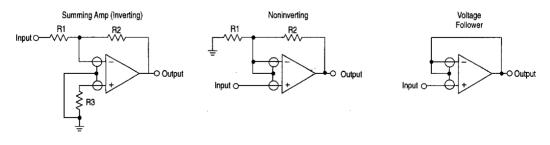
Leakage effects on printed circuit boards can be reduced by encircling the inputs (both sides of pc board) with a conductive guard ring connected to a low impedance potential nearly the same as that of the inputs.

Guard ring electrical connections for common operational amplifier configurations are illustrated in Figure 14. Electrostatic shielding is suggested in high impedance circuits.

Error voltages in external circuitry can be generated by thermocouple effects. Dissimilar metals along with temperature gradients can set up an error voltage ranging in the hundreds of microvolts. Some of the best thermocouples are junctions of dissimilar metals made up of IC package pins and printed circuit boards. Problems can be avoided by keeping low level circuitry away from heat generating elements.

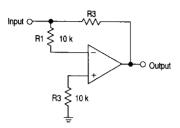
The LM11C is internally compensated, but external compensation can be added to improve stability, particularly when driving capacitive loads.

Figure 14. Guard Ring Electrical Connections for Common Amplifier Configurations



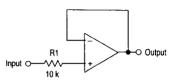
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Figure 15. Input Protection for Summing (Inverting) Amplifier



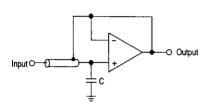
Current is limited by R1 in the event the input is connected to a low impedance source outside the common mode range of the device. Current is controlled by R2 if one supply reverses. R1 and R2 do not affect normal operation.

Figure 16. Input Protection for a Voltage Follower

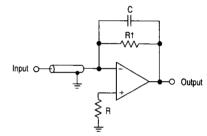


Input current is limited by R1 when the input exceeds supply voltage, power supply is turned off, or output is shorted.

Figure 17. Cable Bootstrapping and Input Shields

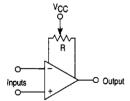


An input shield bootstrapped in a voltage follower reduces input capacitance, leakage, and spurious voltages from cable flexing. A small capacitor from the Input to ground will prevent any instability.



In a summing amplifier the input is at virtual ground. Therefore the shield can be grounded. A small feedback capacitor will insure stability.

Figure 18. Adjusting Input Offset Voltage with Balance Potentiometer



Minimum Adjustment Range (mV)	R (Ω)
±0.4	1.0 k
±1.0	3.0 k
±2.0	10 k
±5.0	100 k

Input offset voltage adjustment range is a function of the Balance Potentiometer Resistance as indicated by the table above. The potentiometer is connected between the two "Balance" pins.